

CLAIMS

1. An organic electronic component with a spacing l between two conductor tracks, electrodes and/or between a conductor track and an electrode of less than $10 \mu\text{m}$, wherein at least one conductor track and/or electrode is arranged in a recess of a lower layer, wherein the recess was produced by means of a layer, that is to say it has steep walls, sharp contours and a relatively rough bottom surface.
2. A process for the production of an organic electronic component in which to produce a conductor track and/or an electrode at least one recess is burnt into a lower layer or the substrate by means of laser and mask, wherein said recess has steep walls, sharp contours and a rough surface at the bottom, and in a subsequent process step is filled with conductive, predominantly organic material.
3. A process as set forth in claim 2 wherein the conductive material is scraped into the recess.
4. A process as set forth in one of claims 2 and 3 wherein excess conductive organic material is wiped away in a process step following the step of filling the recess with said material.
5. A process as set forth in one of claims 2 through 4 wherein a pulsed laser, for example an excimer laser is used.
6. A process as set forth in one of claims 2 through 5 which is performed in a continuous roll-to-roll procedure.

7. A process as set forth in claim 6 wherein the roller which wipes off the excess organic material rotates more slowly than the other rollers.